



Material Content Data Sheet



Sales Product Name	BGF 148 E6327			Issued		29. August 2013		
MA#	MA001077896							
Package	PG-TSNP-14-2			Weight*		4.74 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.072	1.51	1.51	15114	15114
leadframe	non noble metal	zinc	7440-66-6	0.005	0.10		994	
	non noble metal	tin	7440-31-5	0.006	0.12		1242	
	non noble metal	chromium	7440-47-3	0.007	0.15		1491	
	non noble metal	copper	7440-50-8	2.335	49.31	49.68	493090	496817
wire	noble metal	gold	7440-57-5	0.087	1.83	1.83	18345	18345
encapsulation	organic material	carbon black	1333-86-4	0.010	0.20		2012	
	plastics	epoxy resin	-	0.276	5.84		58362	
	inorganic material	silicondioxide	60676-86-0	1.620	34.21	40.25	342125	402499
leadfinish	non noble metal	tin	7440-31-5	0.136	2.86	2.86	28629	28629
plating	noble metal	silver	7440-22-4	0.136	2.88	2.88	28769	28769
glue	plastics	epoxy resin	-	0.009	0.20		1965	
	noble metal	silver	7440-22-4	0.037	0.79	0.99	7862	9827
*deviation	< 10%	Sum in total:				100,00		1000000

Important Remarks:

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